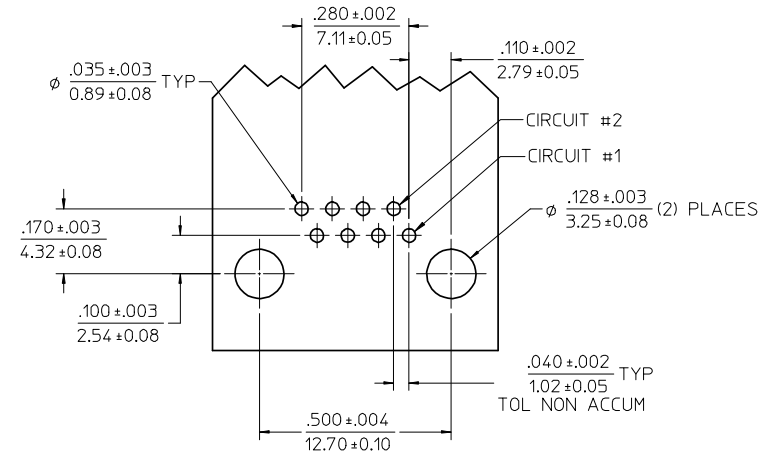
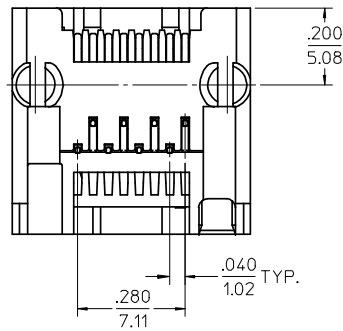
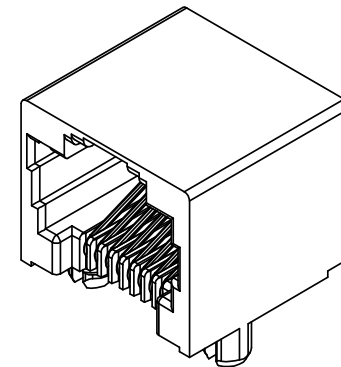
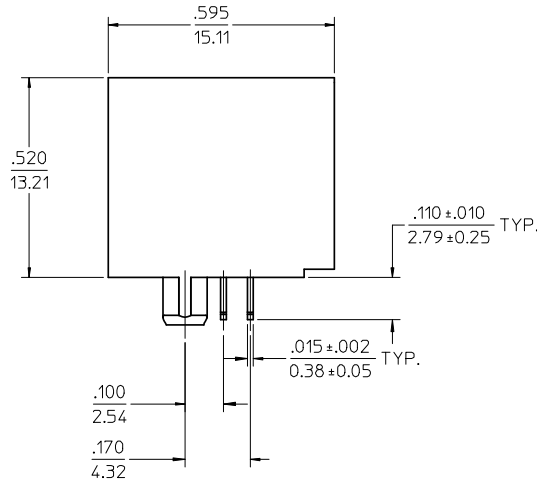
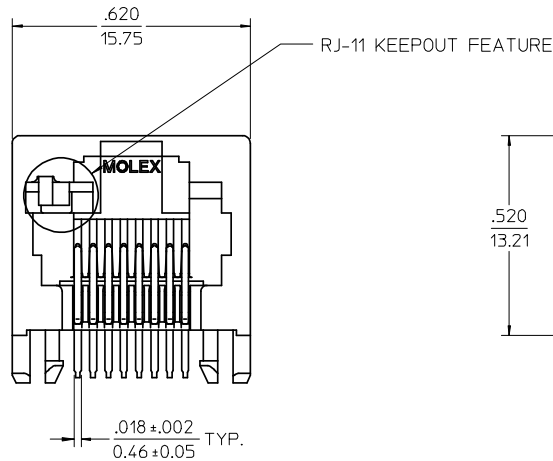


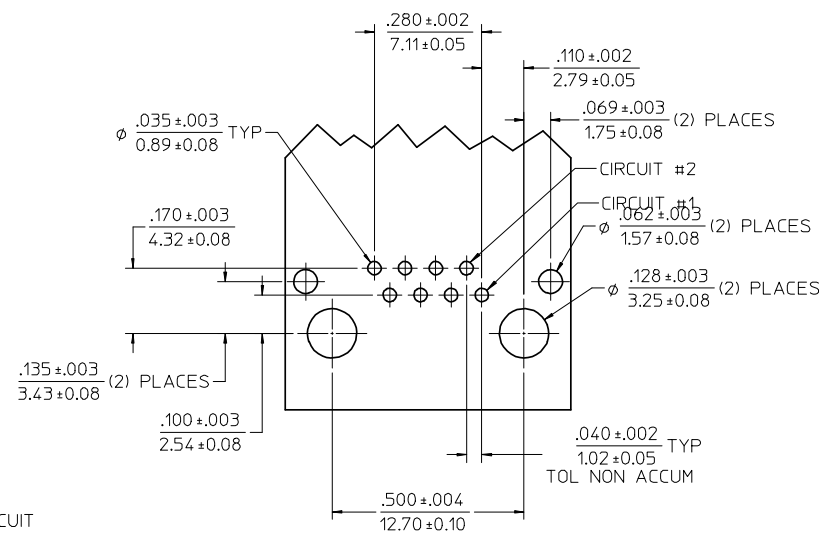
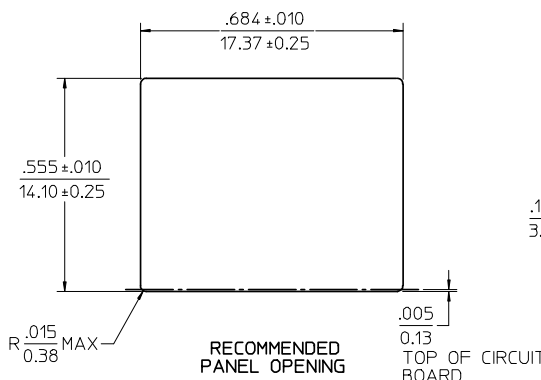
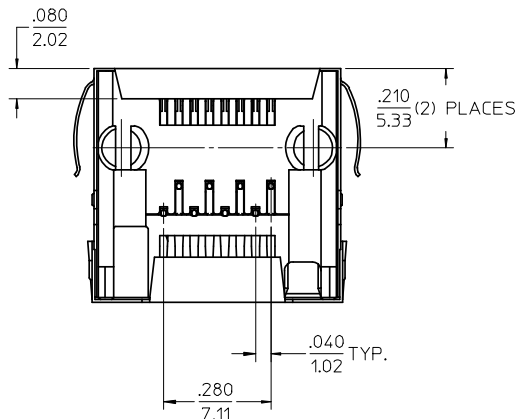
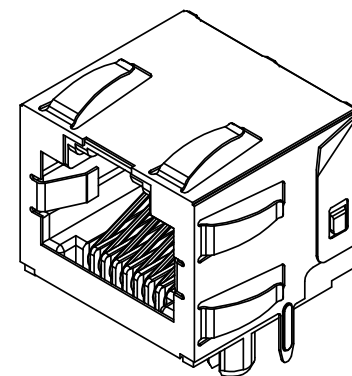
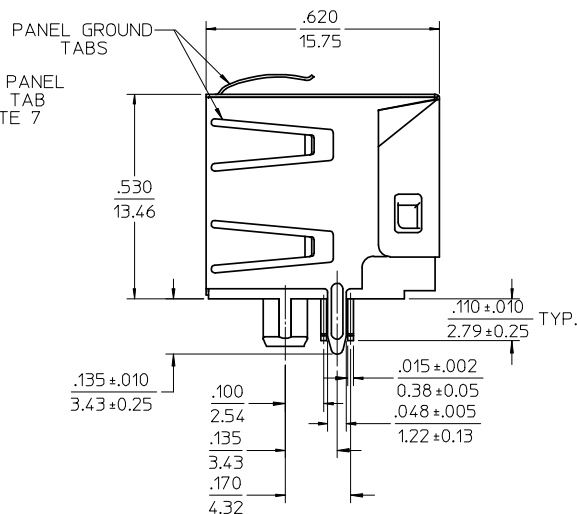
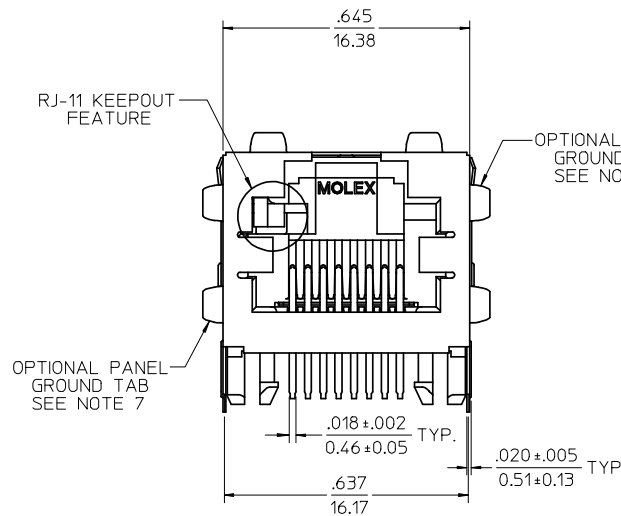


PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PCB THICKNESS: .062/1.57

NOTES:

- 1) MATERIAL:
HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE
- 2) FINISH:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO ROHS
DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD
IN THE PC TAILS.
- 3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
- 4) PACKAGING SPECIFICATION:
CONNECTOR ASSEMBLIES PACKAGED IN EXTRUDED TUBES PER MOLEX
PACKAGING SPECIFICATION PK-43860-004.
- 5) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
- 6) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
- 7) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC
SPECIFICATION PS-45499-002.

ADD NOTE 7 EC NO: UCP2008-0965 DRWN: IBELL 2007/11/08 CHKD: SCHMIDT 2007/12/04 APPR: FSMITH 2007/12/05 D2	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	 THIRD ANGLE PROJECTION	
				mm	INCH	DRAWN BY MKAMAR	DATE 00/03/07	TITLE RJ-45 INVERTED MODULAR JACK ASSEMBLY WITH RJ-11 KEEPOUT FEATURE		
			4 PLACES	± ---	± ---	CHECKED BY	DATE			
			3 PLACES	± ---	± ---	MKAMAR	00/03/07			
			2 PLACES	± ---	± ---	APPROVED BY	DATE			
			1 PLACE	± ---	± ---	JROBERTS	00/03/07			
			ANGULAR ±1/2°		MATERIAL NO. 446200001		DOCUMENT NO. SD-44620-001			SHEET NO. 1 OF 4
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



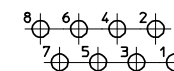
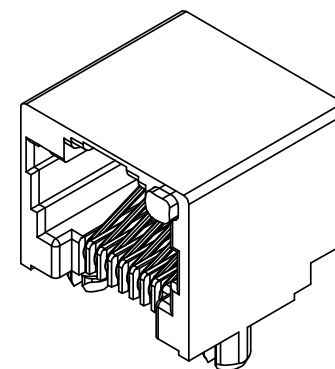
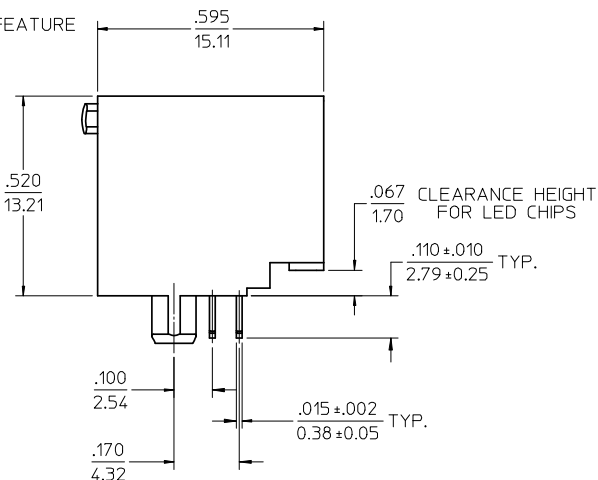
PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PCB THICKNESS: .062/157

- NOTES:
- 1) MATERIAL:
HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE
SHIELD: BRASS
 - 2) FINISH:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
SHIELD:
*100 MICROINCHES (2.54 MICROMETERS) NICKEL OVER 50 MICROINCHES (1.27 MICROMETERS) COPPER UNDERPLATE, PCB GROUND TABS DIPPED IN TIN
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD IN THE PC TAILS AND/OR SHIELD.
 - 3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
 - 4) PACKAGING SPECIFICATION:
CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS PER MOLEX PACKAGING SPECIFICATION PK-43860-005.
 - 5) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
 - 6) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
 - 7) AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS OMITTED FOR SIDE TO SIDE STACKABILITY, PER THE ASSEMBLY MATERIAL NUMBER TABLE.
 - 8) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

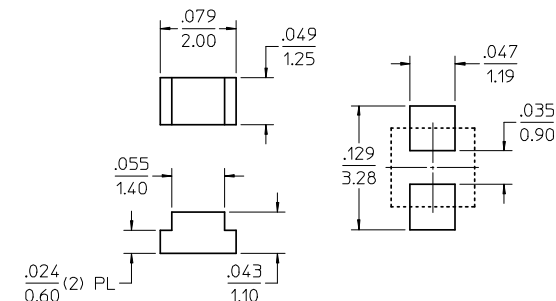
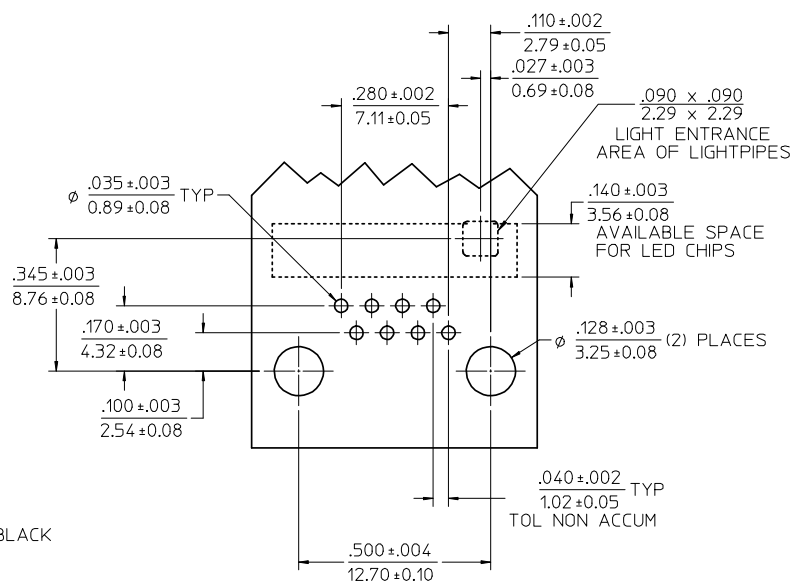
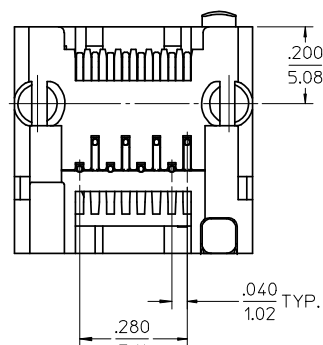
ASSEMBLY MATERIAL NUMBER	PANEL GROUND TABS
446200002	ALL
446200003	SEE NOTE 7

ADD NOTE 8 EC NO: UCP2008-0965 DRWN: BELL 2007/11/08 CHKD: LSCMIDT 2007/12/04 APPR: FSMITH 2007/12/05 REV: D2	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	
				mm	INCH	DRAWN BY MKAMAR	DATE 00/03/07	RJ-45 INVERTED MODULAR JACK ASSEMBLY WITH RJ-11 KEEPOUT FEATURE MOLEX INCORPORATED		
			4 PLACES	± ---	± ---	CHECKED BY	DATE			
			3 PLACES	± ---	± ---	MKAMAR	00/03/07			
			2 PLACES	± ---	± ---	APPROVED BY	DATE			
			1 PLACE	± ---	± ---	JROBERTS	00/03/07	MATERIAL NO.	DOCUMENT NO.	SHEET NO.
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE CHART		SD-44620-001		2 OF 4			
			SIZE (		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

RJ-11 KEEPOUT FEATURE



TYPICAL PC TERMINAL HOLE LAYOUT
SCALE 5:1



RECOMMENDED SMT
LED SOLDER PATTERN
SCALE 10:1
(SEE NOTE 8)

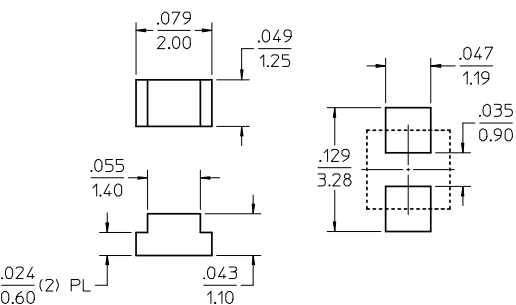
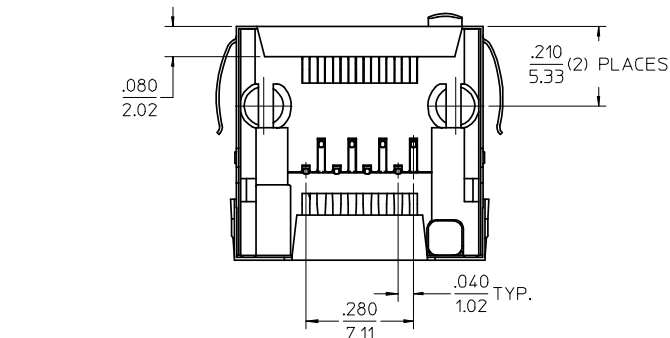
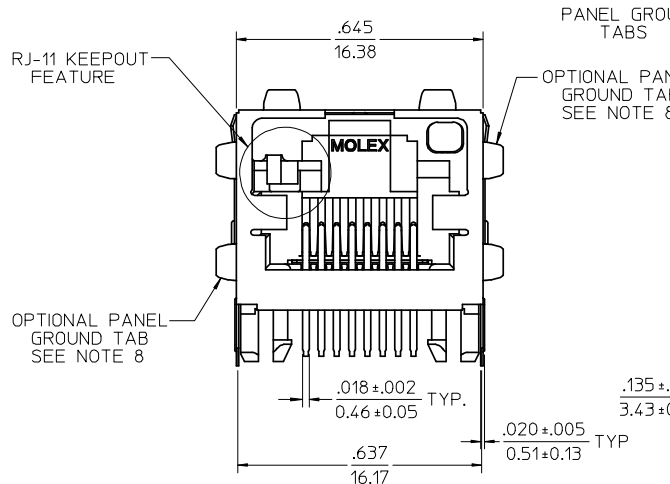
ASSEMBLY MATERIAL NUMBER	LIGHT PIPE MATERIAL
446201004	POLYCARBONATE
446201005	POLYSULFONE

NOTES:

- 1) MATERIAL:
HOUSING: NYLON(IPA), GLASS FILLED, UL94V-0, COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE
LIGHT PIPES:
POLYCARBONATE-WAVE OR HAND SOLDER ONLY (NOT DESIGNED FOR I/R
REFLOW OR CONVECTION REFLOW SOLDER PROCESSES)
POLYSULFONE-MAXIMUM REFLOW TEMPERATURE: 400°F (205°C)
- 2) FINISH:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO ROHS
DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD
IN THE PC TAILS.
- 3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
- 4) PACKAGING SPECIFICATION:
CONNECTOR ASSEMBLIES PACKAGED IN EXTRUDED TUBES PER MOLEX
PACKAGING SPECIFICATION PK-43860-004.
- 5) APPLICATION SPECIFICATION: AS-43860-001
- 6) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
- 7) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
- 8) FOR CROSS REFERENCE OF RECOMMENDED LED'S, SEE MOLEX WEBSITE.
- 9) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC
SPECIFICATION PS-45499-002.

PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PCB THICKNESS: .062/1.57

ADD NOTE 5 & 9 EC NO: UCP2008-0965 DRWG:JBELL 2007/11/08 CHK'D: SCHMIT 2007/12/04 APPR:FSM TH 2007/12/05 D2	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION ⊙ □		
			mm	INCH	DRAWN BY MKAMAR	DATE 00/03/07	TITLE RJ-45 INVERTED MODULAR JACK ASSEMBLY WITH RJ-11 KEEPOUT FEATURE				
			4 PLACES ± --- ± ---		CHECKED BY MKAMAR	DATE 00/03/07	MOLEX MOLEX INCORPORATED				
			3 PLACES ± --- ± ---		APPROVED BY JROBERTS	DATE 00/03/07	DOCUMENT NO. SD-44620-001				
			2 PLACES ± --- ± ---		MATERIAL NO. SEE CHART	SHEET NO. 3 OF 4					
1 PLACE ± --- ± ---		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS									
ANGULAR ±1/2°		SIZE (THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

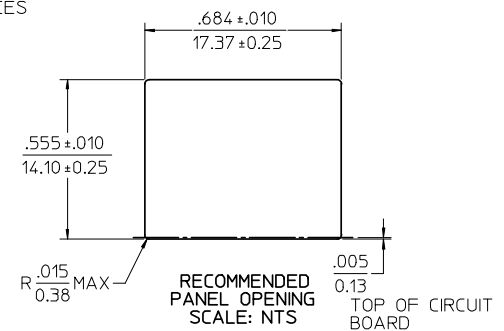
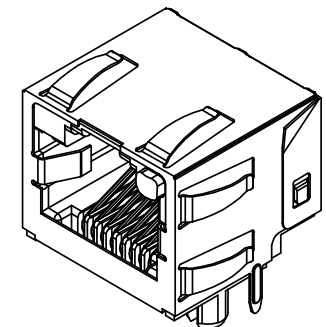


RECOMMENDED SMT
LED SOLDER PATTERN
SCALE 10:1
(SEE NOTE 9)

TYPICAL PC TERMINAL HOLE LAYOUT
SCALE 5:1

PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PCB THICKNESS: .062/157

- NOTES:
- 1) MATERIAL:
HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE
SHIELD: BRASS
LIGHT PIPES:
POLYCARBONATE-WAVE OR HAND SOLDER ONLY (NOT DESIGNED FOR I/R REFLOW OR CONVECTION REFLOW SOLDER PROCESSES)
POLYSULFONE-MAXIMUM REFLOW TEMPERATURE: 400°F (205°C)
 - 2) FINISH:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
SHIELD:
*100 MICROINCHES (2.54 MICROMETERS) NICKEL OVER 50 MICROINCHES (1.27 MICROMETERS) COPPER UNDERPLATE, PCB GROUND TABS DIPPED IN TIN
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD IN THE PC TAILS AND/OR SHIELD.
 - 3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
 - 4) PACKAGING SPECIFICATION: CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS PER MOLEX PACKAGING SPECIFICATION PK-43860-005.
 - 5) APPLICATION SPECIFICATION: AS-43860-001
 - 6) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
 - 7) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
 - 8) AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS OMITTED FOR SIDE TO SIDE STACKABILITY, PER THE ASSEMBLY MATERIAL NUMBER TABLE.
 - 9) FOR CROSS REFERENCE OF RECOMMENDED LED'S, SEE MOLEX WEBSITE.
 - 10) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.



ASSEMBLY MATERIAL NUMBER	LIGHT PIPE MATERIAL	PANEL GROUND TABS
446201006	POLYCARBONATE	ALL
446201007	POLYCARBONATE	SEE NOTE 8
446201008	POLYSULFONE	ALL
446201009	POLYSULFONE	SEE NOTE 8

REV	DESCRIPTION	DATE
D2	ADD NOTE 5 & 10 EC NO: UCP2008-0965 DRWN: BELL CHKD: SCHMIDT APPR: FSMITH	2007/11/08 2007/12/04 2007/12/05

GENERAL TOLERANCES (UNLESS SPECIFIED)
4 PLACES ± .005
3 PLACES ± .004
2 PLACES ± .003
1 PLACE ± .002
ANGULAR ± 1/2°
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	IN/MM
DRAWN BY	DATE
DATE	00/03/07
CHECKED BY	DATE
DATE	00/03/07
APPROVED BY	DATE
DATE	00/03/07
MATERIAL NO.	SEE CHART
DOCUMENT NO.	SD-44620-001
SHEET NO.	4 OF 4

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
4:1	INCH	
RJ-45 INVERTED MODULAR JACK ASSEMBLY WITH RJ-11 KEEPOUT FEATURE		
MOLEX INCORPORATED		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9